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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/709,428	05/05/2004	Cheng-Yen Huang	FTCP0035USA	3427
27765	7590	01/08/2007	EXAMINER	
NORTH AMERICA INTELLECTUAL PROPERTY CORPORATION P.O. BOX 506 MERRIFIELD, VA 22116			TRINH, HOA B	
		ART UNIT	PAPER NUMBER	
		2814		
SHORTENED STATUTORY PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE		
3 MONTHS	01/08/2007	PAPER		

**Please find below and/or attached an Office communication concerning this application or proceeding.**

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

<b>Office Action Summary</b>	Application No.	Applicant(s)
	10/709,428	HUANG, CHENG-YEN
	Examiner Vikki H. Trinh	Art Unit 2814

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --  
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

1) Responsive to communication(s) filed on 27 October 2006.  
 2a) This action is FINAL.                            2b) This action is non-final.  
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

4) Claim(s) 11, 19 and 33-36 is/are pending in the application.  
 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.  
 5) Claim(s) \_\_\_\_\_ is/are allowed.  
 6) Claim(s) 11, 19 and 33-36 is/are rejected.  
 7) Claim(s) \_\_\_\_\_ is/are objected to.  
 8) Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

9) The specification is objected to by the Examiner.  
 10) The drawing(s) filed on \_\_\_\_\_ is/are: a) accepted or b) objected to by the Examiner.  
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).  
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  
 a) All    b) Some \* c) None of:  
 1. Certified copies of the priority documents have been received.  
 2. Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.  
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

#### Attachment(s)

1) <input type="checkbox"/> Notice of References Cited (PTO-892)	4) <input type="checkbox"/> Interview Summary (PTO-413)
2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)	Paper No(s)/Mail Date. _____
3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date _____	5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)
	6) <input type="checkbox"/> Other: _____

## DETAILED ACTION

### *Claim Rejections - 35 USC § 102*

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.  
(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

2. Claims 11, 19, and 33-36 are rejected under 35 U.S.C. 102(e) as being anticipated by

Sutardja et al. (6,903,448) (hereinafter Sutardja).

As to claim 11, 35, Sutardja discloses a packaging comprising a package substrate 1 (figure 7) connected inherently to either a high voltage or a low voltage for turning the device on, a chip 2 (fig. 7) mounted on the package substrate and comprises a plurality of bonding option unit (col. 5, lines 47-48) that comprises a bonding pad (col. 5, lines 47-48); a plurality of first lead frame 72, 52 (fig. 7; the bonding pad has corresponding first lead frame 52, 72 (fig. 7) such that there exists a one-to-one correspondence between the bonding pads and the first lead frames; the first lead frame 52, 72 being connected to either a high voltage or a low voltage (note Vout), wherein the voltage level of the first lead frame 52, 72 is inherently logical opposite of the voltage level of the substrate; wherein the bonding pad (col. 5, lines 47-48) of each bonding option unit is connected to

the package substrate 1 or the corresponding first lead frame 52, 72 for providing two types of bonding options for each bonding option unit (fig. 7).

As to claim 19, Sutardja discloses a method of packaging comprising the steps of providing a package substrate 1 (fig. 7) and connecting inherently to either a high voltage or a low voltage, mounting a chip 2 (fig. 7) on the package substrate 1 and comprising a plurality of bonding option unit (Col. 5, lines 47-48) that comprises a bonding pad; providing a plurality of first lead frame 52,72 (fig. 7) such that there exists a one-to-one correspondence between the bonding pads and the first lead frames; connecting the bonding pad to the substrate 1 or the corresponding first lead frame 52, 72 (fig. 7); the first lead frame 52, 72 (fig. 7) being connected inherently to either a high voltage or a low voltage (note Vout), wherein the voltage level of the first lead frame 52, 72 is inherently logical opposite of the voltage level of the substrate 1 (GND); wherein each bonding pad is selectively connected to the package substrate 1 or the first lead frame 52, 72 (fig. 7) for providing two types of bonding options for each bonding option unit (fig. 7).

As to claims 33 and 34,36, Sutardja further teaches the device and method of providing a plurality of second lead frames 51, 73 (fig. 7), each bonding pad (col. 5, lines 47-48; fig. 7) of the chip 2 (fig. 7) having a corresponding second lead frame 51, 73, wherein the second lead frames 51, 73 are used for inputting signals to the corresponding bonding pad (fig. 7), and each bonding pad (fig. 7) is connected to the substrate 1, the corresponding first lead frame 52, 752 or the corresponding second lead frame 51, 73 (fig. 7) for providing three types of bonding options for each bonding option unit (fig. 7)

such that there exists a one-to-one correspondence between the bonding pads and the first lead frames.

***Response to Arguments***

3. Applicant's arguments with respect to claims 11, 19, and 33-34 have been considered but they are not persuasive.

Claims 11, 19, 33-34 fail to overcome Sutardja, because Sutardja teaches all of the limitation of the claims. In particular, the newly amended phrase "such that there exists a one-to-one correspondence between the bonding pads and the first lead frames" merely reiterates the functionality of the bonding pads relative to the leadframes. Applicants even admit on page 6, lines 20, that Surtadja discloses numerous bonding pads and numerous lead frames that can easily accommodate at least some one-to-one correspondence between the bonding pads and the lead frames. Thus, Surtadja still read on the present invention.

**Conclusion**

4. **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

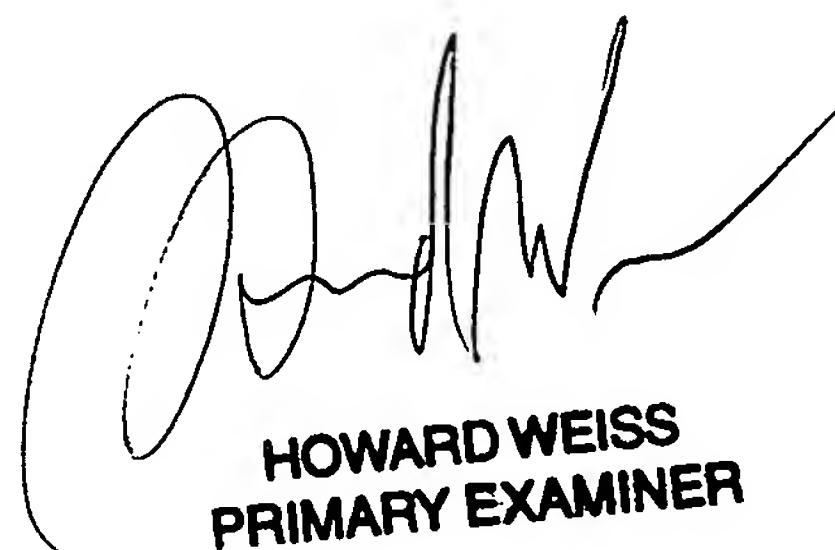
A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event,

however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any request for information regarding to the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Also, status information for published applications may be obtained from either Private PAIR or Public Pair. In addition, status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. If you have questions pertaining to the Private PAIR system, please contact the Electronic Business Center (EBC) at 866-217-9197 (toll free).

Lastly, paper copies of cited U.S. patents and U.S. patent application publications will cease to be mailed to applicants with Office actions as of June 2004. Paper copies of foreign patents and non-patent literature will continue to be included with office actions. These cited U.S. patents and patent application publications are available for download via the Office's PAIR. As an alternate source, all U.S. patents and patent application publications are available on the USPTO web site ([www.uspto.gov](http://www.uspto.gov)), from the Office of Public Records and from commercial sources. Applicants are referred to the Electronic Business Center (EBC) at <http://www.uspto.gov/ebc/index.html> or 1-866-217-9197 for information on this policy. Requests to restart a period for response due to a missing U.S. patent or patent application publications will not be granted.

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HOWARD WEISS  
PRIMARY EXAMINER